rather than continuously processing the organic electronic devices on a fragile, flexible substrate, the organic electronic devices are continuously processed on a flexible, robust substrate without hermetic properties. Subsequent to organic electronic device fabrication, a fragile hermetic barrier is added to the organic electronic device, thereby forming a hermetic organic device package. Processing techniques such as scribing and embossing may be advantageously employed to generate fine features in electrodes of the organic electronic devices without damaging the fragile hermetic barrier. These organic device packages may find application in various fields such as display applications, area lighting applications and other applications.

While only certain features of the invention have been illustrated and described herein, many modifications and changes will occur to those skilled in the art. It is, therefore, to be understood that the appended claims are intended to cover all such modifications and changes as fall within the true spirit of the invention.

The invention claimed is:

1. An organic device package comprising:

a flexible substrate having a topside and a bottom side;

an organic electronic device having a first side and a second side disposed on the topside of the flexible substrate;

a first barrier layer having a first inner surface and a first outer surface disposed on the bottom side of the flexible substrate, wherein the first barrier layer is substantially planar;

a second barrier layer having a second inner surface and a second outer surface disposed proximate to the first side of the organic electronic device, wherein the second barrier layer is substantially planar; and

an edge encapsulating material disposed about the perimeter of the organic electronic device between the first and second barrier layers, wherein the edge encapsulating material is coupled directly to each of the first inner surface of the first barrier layer and the second inner surface of the second barrier layer and configured to hermetically seal peripheral edges of the organic device package.

2. The organic device package of claim **1**, further comprising a bonding material disposed on each of the inner surfaces of the first and second barrier layers, wherein the bonding material is configured to affix the first and second barrier layers to the flexible substrate and the organic electronic device respectively.

3. The organic device package of claim **1**, wherein the edge encapsulating material is disposed on one of the first barrier layer, or the second barrier layer, or combinations thereof.

4. The organic device package of claim **1**, wherein the edge encapsulating material is injected between the first and second barrier layers.

5. The organic device package of claim **1**, wherein the edge encapsulating material comprises a material, wherein the material is similar to a material of the first barrier layer, or a material of the second barrier layer, or combinations thereof.

6. The organic device package of claim **1**, wherein the edge encapsulating material comprises a metal, or a metal alloy having a low melting point.

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